

Declaration of Conformity

We

NEC DISPLAY SOLUTIONS, LTD.

(MANUFACTURER'S NAME)

of

**686-1, NISHIOI, OI-MACHI, ASHIGARAKAMI-GUN,
KANAGAWA 258-8533, JAPAN**

(MANUFACTURER'S ADDRESS)

declare under our sole responsibility that the product

21.3" Color LCD Monitor, Model MultiSync LCD2190UXp (L215GW)

is in conformity with the provisions of:

- **Directive 2002/95/EC of the European Parliament and of the Council of 27 January 2003 ("RoHS Directive")**
- **Commission Decision 2005/618/EC of 18 August 2005**
- **Commission Decision 2005/717/EC of 13 October 2005**
- **Commission Decision 2005/747/EC of 21 October 2005**

(NAME OF THE AUTHORIZED PERSON)

Kunio Jouhan

(TITLE OF AUTHORIZED PERSON)

**General Manager,
Quality Assurance Department**

(PLACE AND DATE OF ISSUE)

Kanagawa, Japan May.16,2006

(SIGNATURE OF THE AUTHORIZED PERSON)



In conformity with the provisions of the Directive 2002/95/EC and the Commission Decisions shown in Page 1 of 2, products are nonetheless considered “RoHS compliant”, when content concentration of restricted substances in a homogeneous part is within the following threshold limits:

- Cadmium : 100ppm or less.
- Lead, Hexavalent Chromium, Mercury, PBDE, PBB : 1000ppm or less.

The following applications are exempted from the RoHS Directive (Directive 2002/95/EC and Commission Decisions shown in Page 1 of 2):

No.	Substance	Major Application or Scope
1	Mercury	Mercury in compact fluorescent lamps not exceeding 5 mg per lamp.
2		Mercury in straight fluorescent lamps for general purposes not exceeding -halophosphate:10mg -triphosphate with normal lifetime:5mg -triphosphate with long lifetime:8mg
3		Mercury in straight fluorescent lamps for special purposes.
4		Mercury in other lamps not specifically mentioned in this Annex.
5	Lead	Lead in glass of cathode ray tubes, electronic components and fluorescent tubes.
6		Lead as an alloying element in steel containing up to 0.35% lead by weight, aluminum containing up to 0.4 % lead by weight and as a copper alloy containing up to 4 % lead by weight.
7		Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead),
		lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission as well as network management for telecommunication,
		lead in electronic ceramic parts (e.g. piezoelectronic devices).
8	Cadmium	Cadmium and its compounds in electrical contacts and cadmium plating except for applications banned under Directive 91/338/EEC(1) amending Directive 76/769/EEC(2) relating to restrictions on the marketing and use of certain dangerous substances and preparations.
9	Hexavalent Chromium	Hexavalent chromium as an anti-corrosion of the carbon steel cooling system in absorption refrigerators.
9a	PBDE	DecaBDE in polymeric applications;'
9b	Lead	Lead in lead-bronze bearing shells and bushes'.
10	-	-
11	Lead	Lead used in compliant pin connector systems.
12		Lead as a coating material for the thermal conduction module c-ring.
13	Lead and cadmium	Lead and cadmium in optical and filter glass.
14	Lead	Lead in solders consisting of more then two elements for the connection between the pins and package of microprocessors with a lead content of more then 80% and less then 85% by weight.
15		Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages.'